

## Refine Search

### Search Results -

Terms	Documents
L2 and polyimide	2

Database:

US Pre-Grant Publication Full-Text Database  
US Patents Full-Text Database  
US OCR Full-Text Database  
EPO Abstracts Database  
JPO Abstracts Database  
Derwent World Patents Index  
IBM Technical Disclosure Bulletins

Search:

L3

Refine Search

Recall Text

Clear

Interrupt

### Search History

DATE: Friday, June 25, 2004   [Printable Copy](#)   [Create Case](#)Set Name Query

side by side

Hit Count Set Name

result set

*DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI; PLUR=YES; OP=ADJ*L1    ishikawa-seiji\$.in. or hayashi-koji\$.in. or sonoyama-kenji\$.in.1471    L1L2    L1 and dicing2    L2L3    L2 and polyimide2    L3

END OF SEARCH HISTORY

## Refine Search

### Search Results -

Terms	Documents
L9 and strength	13

Database:

US Pre-Grant Publication Full-Text Database  
 US Patents Full-Text Database  
 US OCR Full-Text Database  
 EPO Abstracts Database  
 JPO Abstracts Database  
 Derwent World Patents Index  
 IBM Technical Disclosure Bulletins

Search:

L10

Refine Search

Recall Text

Clear

Interrupt

### Search History

DATE: Friday, June 25, 2004   [Printable Copy](#)   [Create Case](#)

#### Set Name Query

side by side

#### Hit Count Set Name

result set

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI; PLUR=YES; OP=ADJ

<u>L1</u>	dicing	20543	<u>L1</u>
<u>L2</u>	semiconductor	1401292	<u>L2</u>
<u>L3</u>	polyimide	130445	<u>L3</u>
<u>L4</u>	polyimidesiloxane or polyimidosiloxane or (polyimide with siloxane)	2155	<u>L4</u>
<u>L5</u>	adhesive	1005794	<u>L5</u>
<u>L6</u>	l3 with L5	11314	<u>L6</u>
<u>L7</u>	l4 and L6	530	<u>L7</u>
<u>L8</u>	l1 and L7	17	<u>L8</u>
<u>L9</u>	l2 and L8	16	<u>L9</u>
<u>L10</u>	l9 and strength	13	<u>L10</u>

END OF SEARCH HISTORY